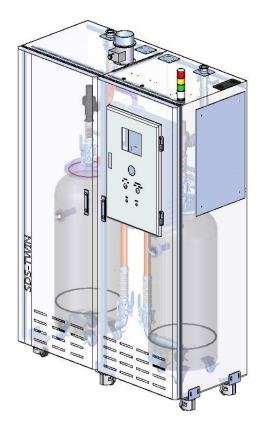
SDS-500 "TWIN"

"DRY" TYPE POU ABATEMENT



Exhaust solution for high-volume semiconductor manufacturing



Applications

> Semiconductor processes

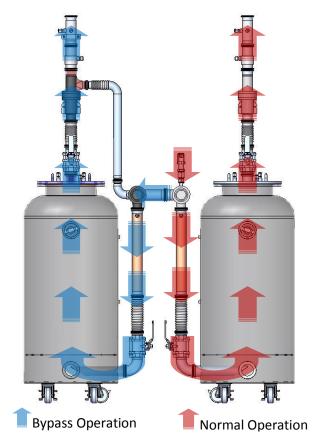
Features

- > Primary 80 liter cartridge x2
- > Bypass cartridge
- > Standard N2 purge function
- > 80% color change sight tube
- > Double-acting pneumatic valves for power failure ride through
- > Pressure monitoring and relief
- > N2 eductor for inlet pressure control
- > Temperature monitoring and auto N2 purge function
- > Gas monitoring options
- > In-situ oxidation option

Benefits

- > Virtually zero unscheduled downtime with bypass cartridge
- > High abatement efficiency
- > Designed for target gas emissions level below TLV
- > Low overall CoO
- > HVM (high volume manufacturing) proven

System Specifications



• Total System Capacity: 150 slm

• MTBF: >8,300 hours

MTTR: <4 hour

MTTP: <3 hour

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Dimensions and Weight

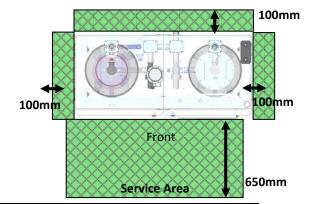
SDS-500

Dimension 1300 x 590 x 1740

(W x D x H in mm)

Weight 480 (with Resin)

Utilities



Item	Туре	Typical Usage	Connection Type
Electricity	208VAC1 Phase	0.1 KW	5A
N2	3 ~ 6 kg/cm ²	40 LPM	1/4" SS compression
Air or N2	5 ~ 6.5 kg/cm ²	<0.1 LPM	1/4" SS compression (Valve Operation)
Gas Exhaust	-50 ~ -100 mmH2O	0.2 m ³ /min	KF40 Flange (2 ports)
Cabinet Exhaust	-50 ~ -60 mmH2O	1 m³/min	Ø100mm

Dry Media

Application	Adsorbent	Target Gas	Density
Acid gases	GST C1	Cl2, BCl3, HBr, HCl, HF	0.7
Basic gases	GST DB	NH3	0.75
Flammable gases	GST H2	SiH4, PH3, AsH3, B2H6, DCS	0.9
VOC	GST M1	VOCs, NH3	0.75
Sulfide gases	GST DS	H2S, SO2	0.7

- A combination of dry media may be used for optimum abatement efficiency and lifetime
- Other dry media types available

Environment

Temperature: 5 ~ 30 °C

• Relative Humidity: < 65%

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